PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Seiyo NAKASHIMA	01/21/2009
Tomoyuki YAMADA	01/21/2009
Masakazu SHIMADA	01/21/2009

RECEIVING PARTY DATA

Name:	Hitachi Kokusai Electric, Inc.
Street Address:	14-1 Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12363045

OP $40.00 12363045

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	JIM-6924
NAME OF SUBMITTER:	Nora Colston

Total Attachments: 1
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ASSIGNMENT

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to the undersigned by Hitachi Kokusai Electric, Inc., a corporation organized under the laws of Japan, located at 14-1 Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric, Inc., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SUBSTRATE PROCESSING APPARATUS, METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, AND PROCESS TUBE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kokusai Electric, Inc., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric, Inc.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)	Date Signed
1) Seiyo Nakashima Seiyo Nakashima	January 21, 2009
2) Tomoyuki Yamada Tomoyuki Yamada	January 21, 2009
3) Masakazu Shimada	January 21, 2009